

## Jones Group Objectives & Goals

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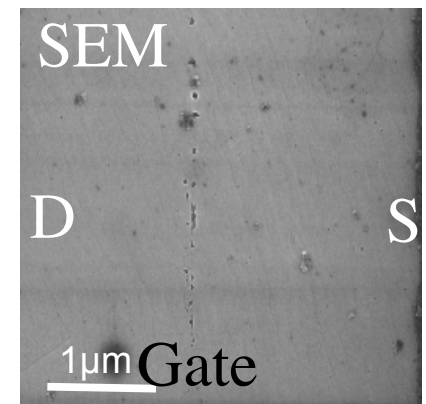
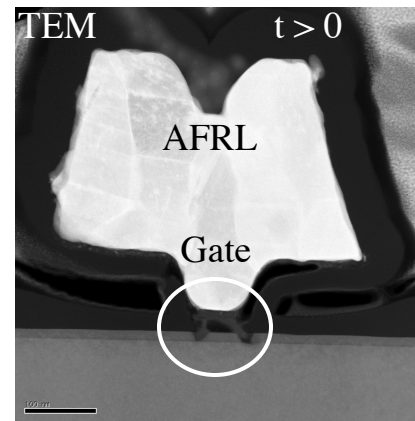
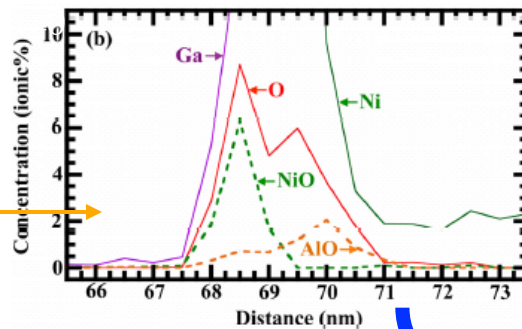
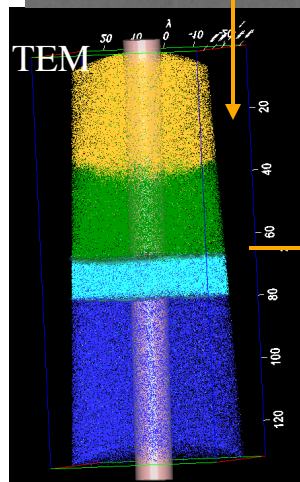
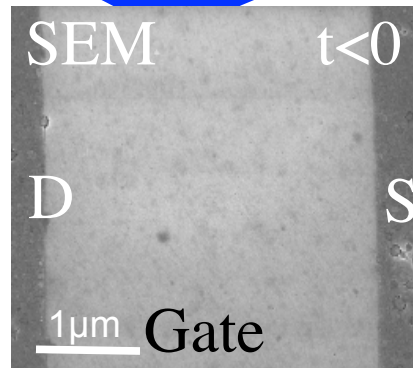
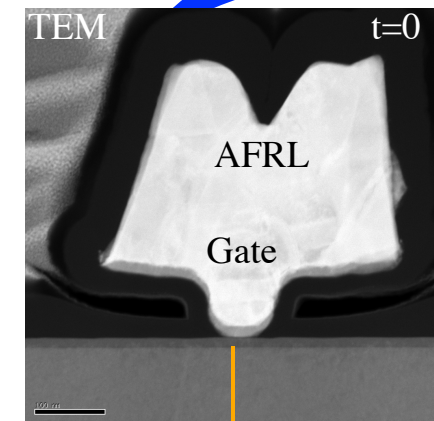
- Identify and Characterize defects and reliability issues in III-V semiconductors after accelerated life-time testing using:
  - SEM
  - TEM
  - Atom Probe Tomography (APT)
- Goals
  - Provide an understanding for the structural and chemical failure mechanisms in AlGaN/GaN HEMTs in order to improve reliability simulation.

# TEM, LEAP, and Interfacial Defects of AlGaN/GaN HEMTs

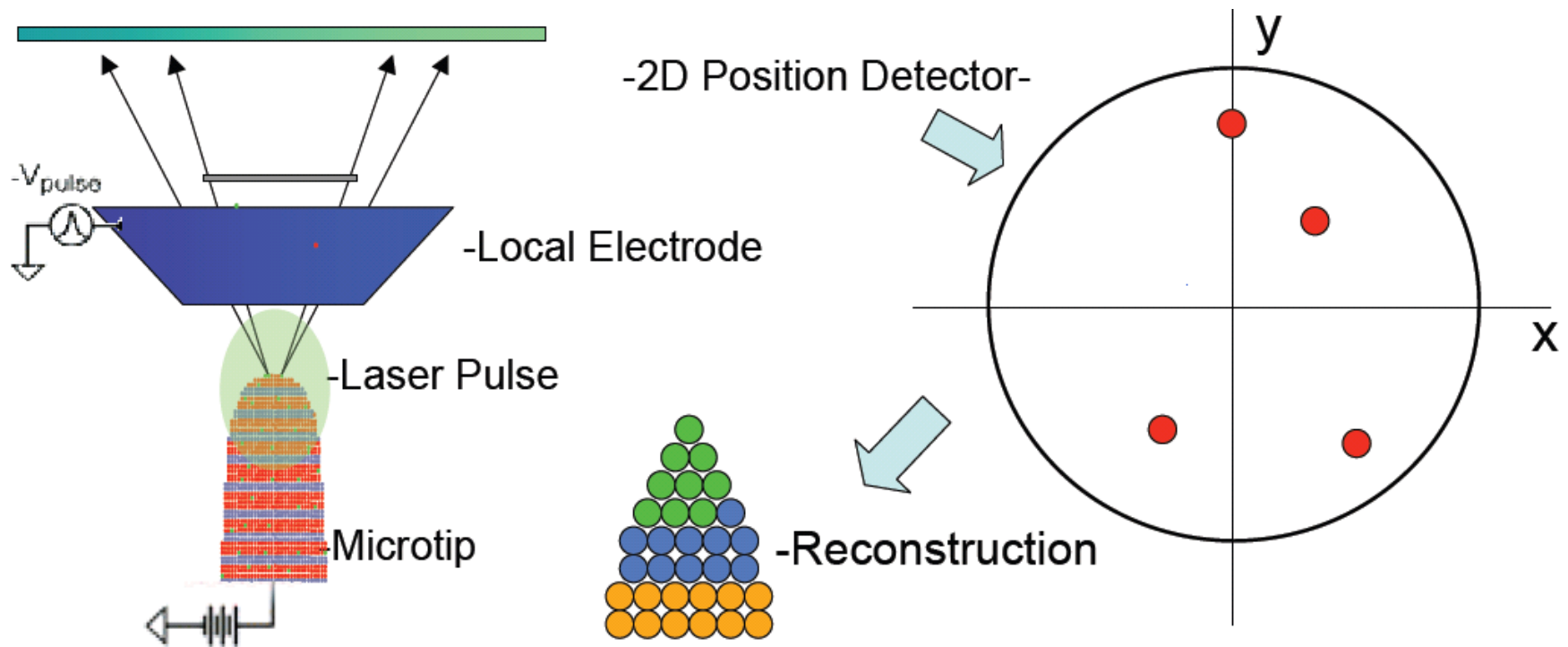
$t=0$ , As Built

FLOORS

$t>0$ , Degradation



# How Does APT Work?



## Data collected:

- (x,y) position of impact on detector
- Impact sequence number
- Time of flight

reconstruction

## Resulting analysis:

- (x,y) position of atom in plane of the tip
- Position of atom along z-axis
- Element identification

# Characterize Gate Metal Reaction

- TEM (STEM-HAADF)

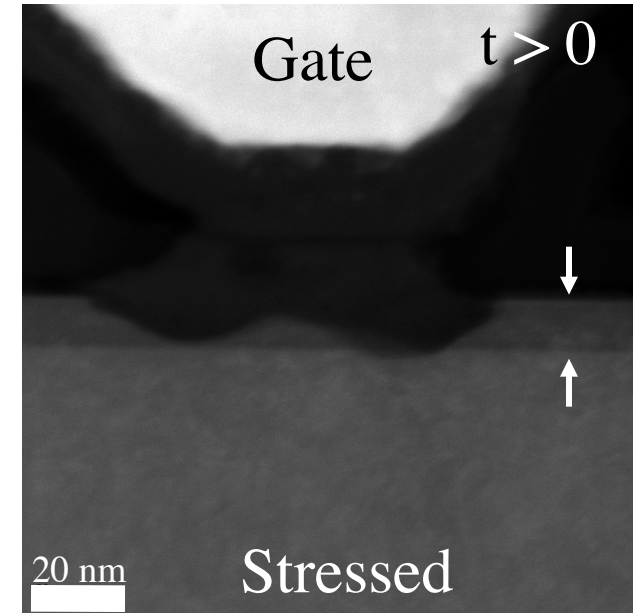
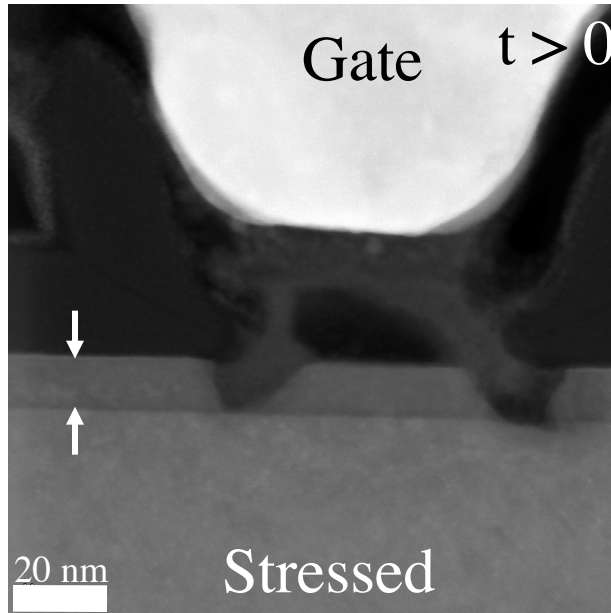
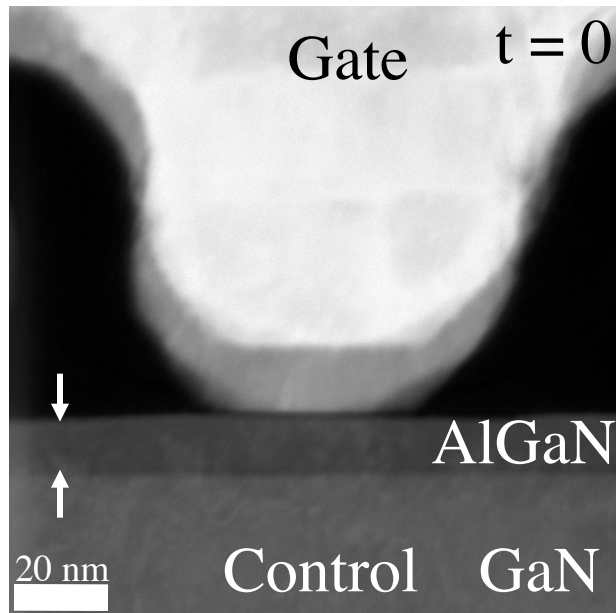
- 100nm  $L_G$
- Ni-gate

## Stress Conditions

$V_{DS} = 5V$   
 $V_G = -10V$  to  $-42V$   
• 1 min steps

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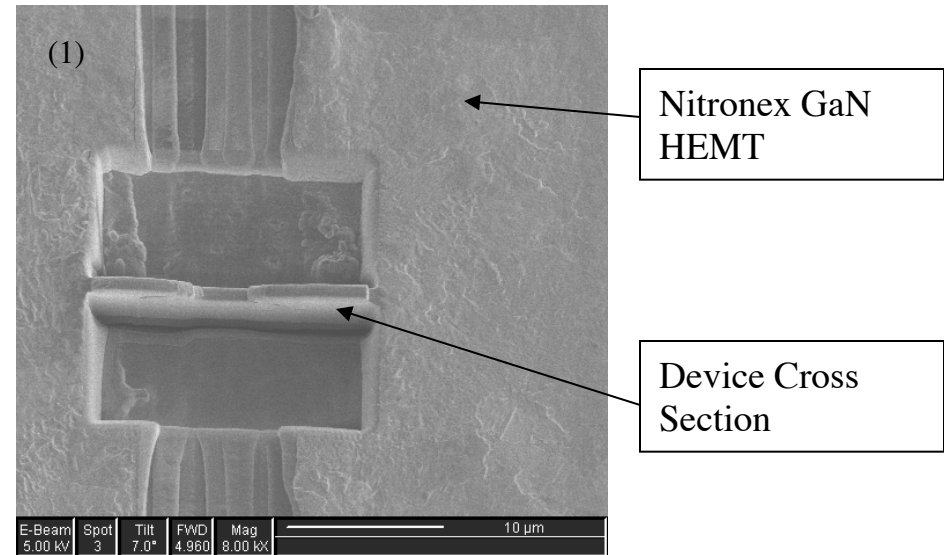


- APT would provide 3D chemical analysis and provide additional chemical information such as if segregation occurred.

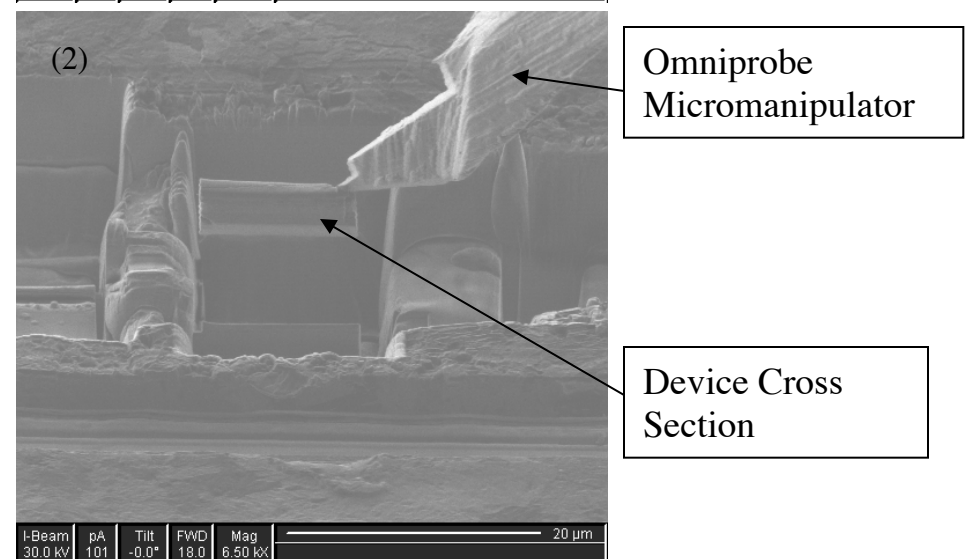


# Constructing LEAP Tips of AlGaIn/GaN HEMTs

1) FIB device cross section



2) Sample lift out

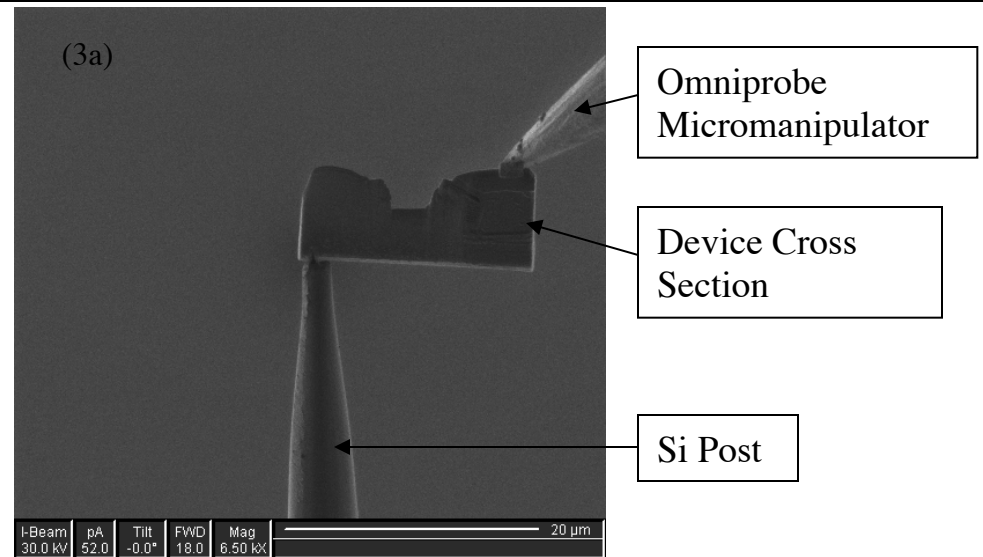


3) Mount on silicon post

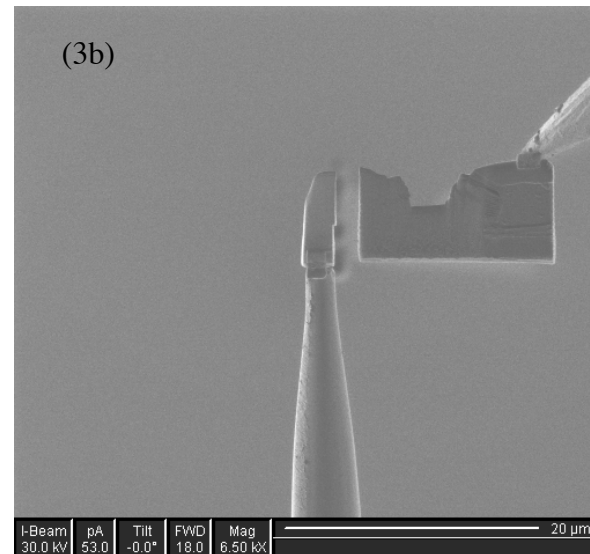
4) Sharpen tip

# Constructing LEAP Tips

- 1) FIB device cross section
- 2) Sample lift out
- 3) Mount on silicon post
  - a) Attach to post



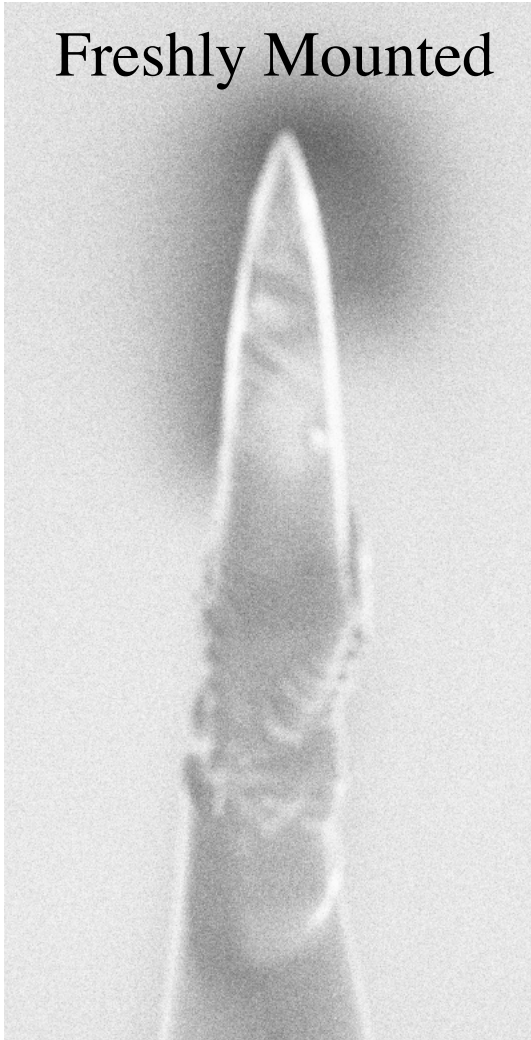
- b) Detach from cross section



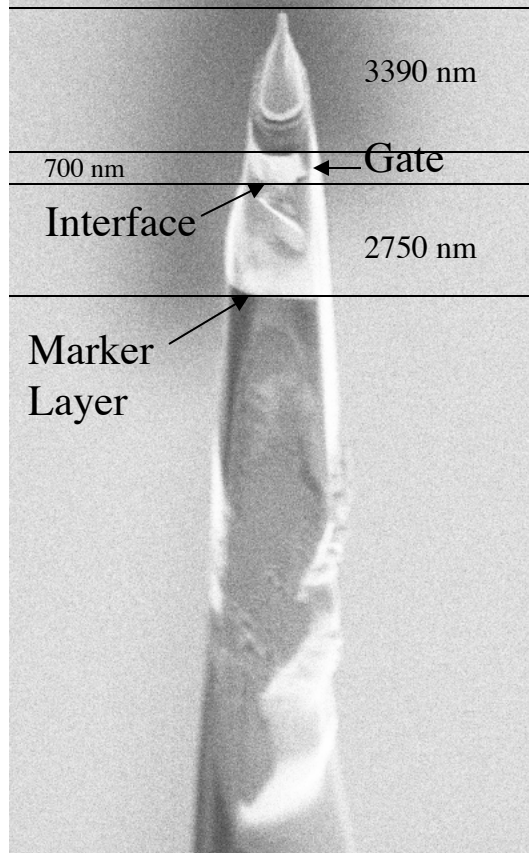
- 4) Sharpen tip

# Making Site Specific LEAP Tips

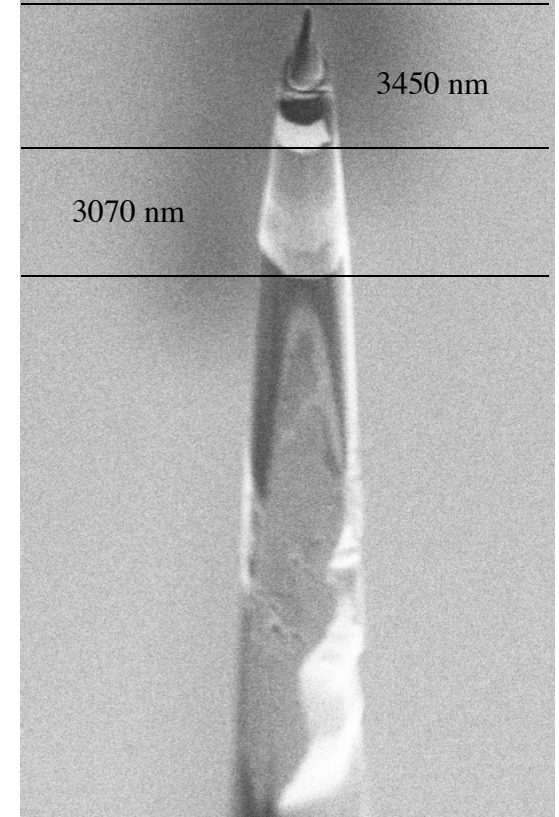
Freshly Mounted



Middle of 1<sup>st</sup> Mill

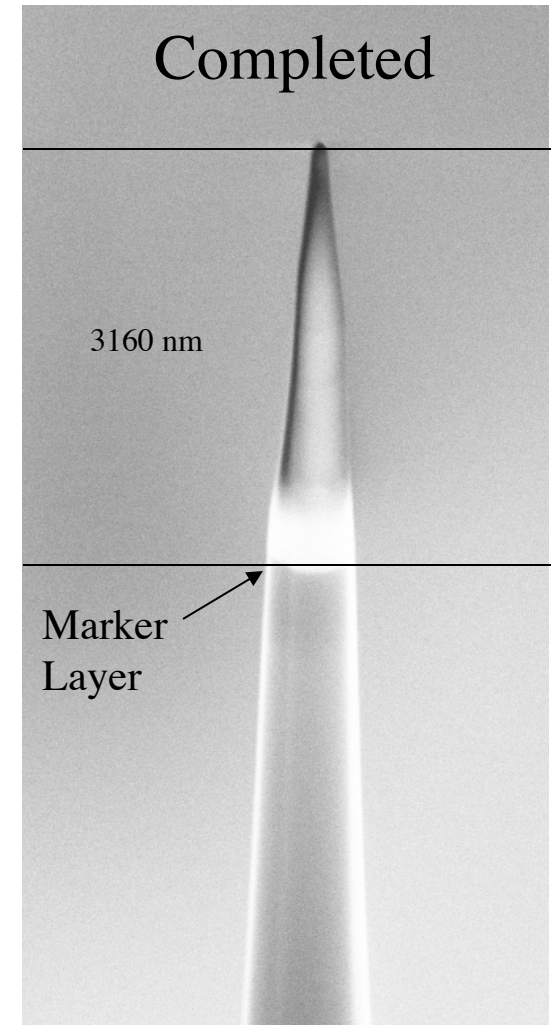
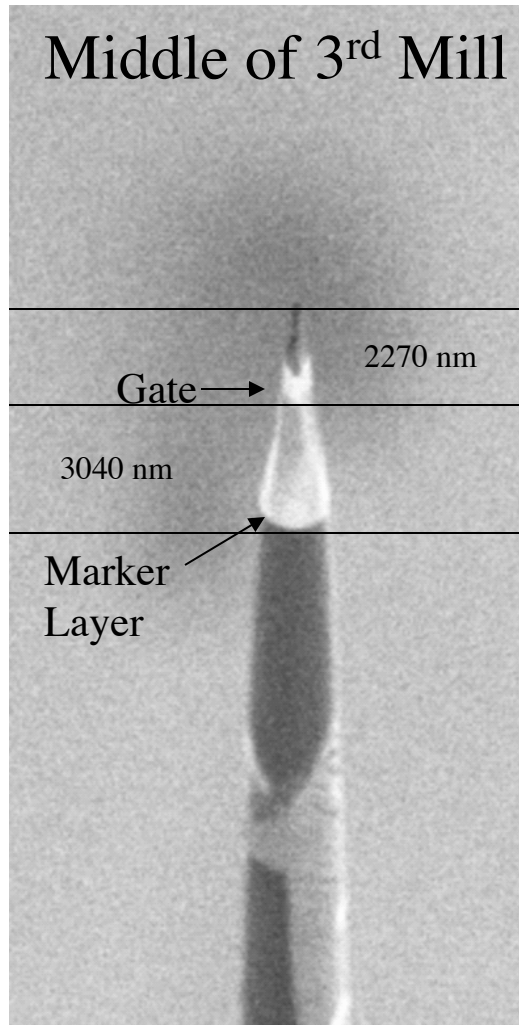
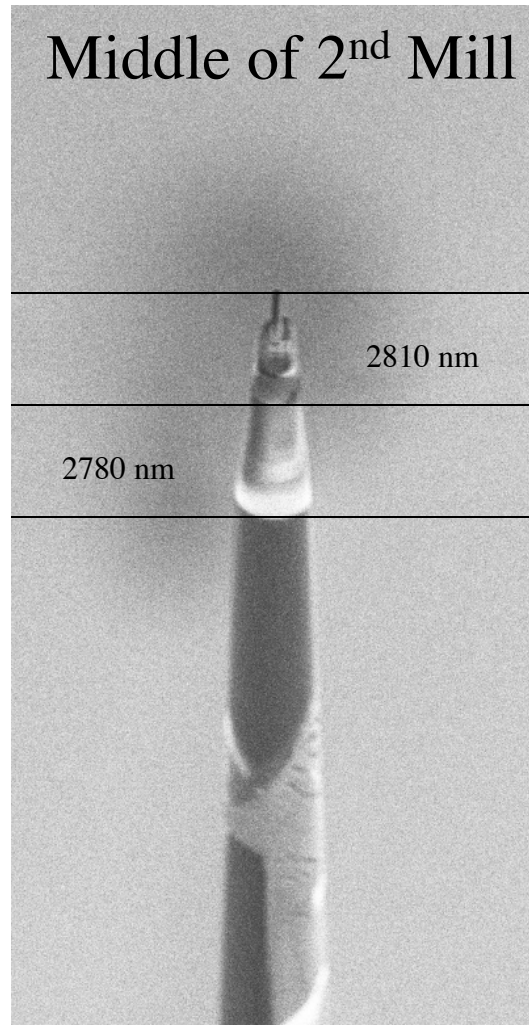


End of 1<sup>st</sup> Mill





# Making Site Specific LEAP Tips





# Analytical Instruments for Metrology

## Quantitative Performance Metrics

	<b>SIMS</b>	<b>TEM</b>	<b>APT</b>
<b>3D Volume Imaging</b>	No	Yes with Limitations	Yes
<b>Spatial resolution (compositional)</b>	50 nm laterally 2 nm depth	0.2 nm laterally 5 nm depth	0.4 nm laterally 0.2 nm depth
<b>Image resolution</b>	NA	0.1 nm	0.2 nm
<b>Sensitivity</b>	<1 ppm ( $<5 \times 10^{16} \text{ cm}^{-3}$ )	~1000 ppm ( $5 \times 10^{19} \text{ cm}^{-3}$ )	~20 ppm ( $1 \times 10^{18} \text{ cm}^{-3}$ )
<b>Planar specimens</b>	Yes	Yes	Yes

- APT would provide 3D chemical and structural analysis on a length scale not provided by current characterization tools

# Summary of Jones Group

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- APT is a powerful characterization tool.
  - Used in conjunction with complimentary TEM techniques (EDS, EELS)
    - Collaborating with Prof. Hono in Tsukuba on APT
    - Collaborating with Prof. Smith ASU on EELS
- Developing Deprocessing Techniques to allow SEM studies of spatial distribution and quantification of defects.
  - Collaborating with Steve Tetlak (AFRL) on EBIC
- Various characterization methods being used to provide chemical information of sub-nm to nano-scale defects in AlGaIn/GaN HEMTs and to identify defects and help propose failure mechanisms